

STANDARD SINGLE SIDED SHOWN 20842610XX  
 BELLY-TO-BELLY APPLICATION USE 20842615XX  
 LOW SPEED SIGNAL PIN LOCATION IS REVERSED  
 IN ORDER TO STAGGER PCB PIN HOLE FIELD  
 SEE SHEET 5 & 7

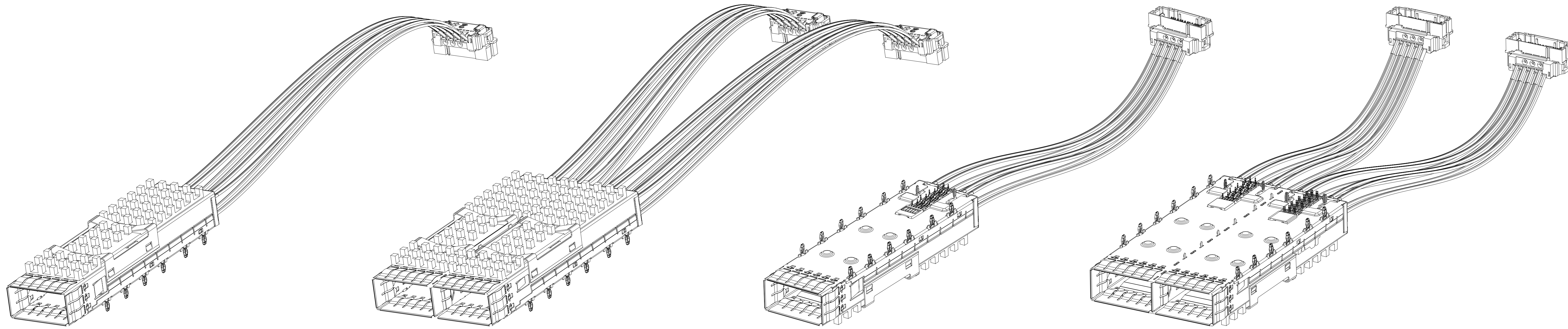
- NOTES:
- CABLE LENGTH DEPENDS ON WIRE GAUGE, DATA RATE AND HOST BOARD DRIVER CAPABILITIES.
  - MATERIALS:
    - CAGE - STAINLESS STEEL
    - HEAT SINK - ALUMINUM - NICKEL PLATED
    - SPRING FINGERS - STAINLESS STEEL
    - HEAT SINK CLIP - STAINLESS STEEL
  - TWINAX CABLE (HIGH SPEED)
    - SHIELD - ALUMINUM/POLYESTER FOIL WRAP
    - SIGNAL PAIR - 34AWG SOLID SILVER PLATED COPPER
    - DRAIN - 34AWG SOLID SILVER PLATED COPPER
    - CONFORMS TO UL VW-1
    - IMPEDENCE - 100 OHMS
  - RoHS COMPLIANT. NO EXEMPTIONS.
  - P2: BIPASS WITH NEARSTACK RECEPTACLE PN FOR GEN 2.0  
 MATES WITH NEARSTACK PLUG PN 20331622XX (GEN 2.0)
  - MARK WITH PART NUMBER SERIAL NUMBER  
 PART NUMBER: SEE PART NUMBER TABLE  
 SERIAL NUMBER:  
 YY - YEAR  
 DDD - DAY OF THE YEAR  
 L - MANUFACTURE LOCATION  
 SSSS - SERIAL NUMBER (0001-9999)

SYMBOLS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
▽ = 0	DIMENSION UNITS	SCALE	CURRENT REV DESC: UPDATE NOTES 5 FOR CLARIFICATION SHALL MATE GEN 2.0 BIPASS WITH GEN 2.0 PLUG
▽ = 0	mm	1:1	EC NO: 701299
▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRWN: LLI05 2022/03/02
▽ = 0	ANGULAR TOL	± °	CHK'D: BCHEN06 2022/04/08
▽ = 0	4 PLACES	±	APPR: BCHEN06 2022/04/08
▽ = 0	3 PLACES	±	INITIAL REVISION:
▽ = 0	2 PLACES	± 0.13	DRWN: SVANG01 2018/06/12
▽ = 0	1 PLACE	± 0.25	2018/11/09
▽ = 0	0 PLACES	±	APPR: ADTUCKER
⊠ = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION
■ = 0			DRAWING SERIES
▽ = 0			D-SIZE 208426
DOCUMENT STATUS		P1	RELEASE DATE 2022/04/08 04:59:14
DOCUMENT NUMBER		2084261000	DOC TYPE PSD
DOC PART		000	REVISION G
MATERIAL NUMBER		SEE P/N TABLE	CUSTOMER GENERAL MARKET
SHEET NUMBER		1 OF 9	

**molex**

ZQSFP BIPASS P2B 1XN POWER TO BOARD

PRODUCT CUSTOMER DRAWING



1X1 STANDARD  
TOP OF BOARD

PART NUMBER	NEARSTACK HIGH SPEED LENGTH (MM)
2084261002	150
2084261003	200
2084261004	300
2084261005	400
2084261006	450
2084261007	500

1X2 STANDARD  
TOP OF BOARD

PART NUMBER	NEARSTACK HIGH SPEED LENGTH (MM)
2084262002	150
2084262003	200
2084262004	300
2084262005	400
2084262006	450
2084262007	500

1X1 BELLY TO BELLY  
BOTTOM OF BOARD

PART NUMBER	NEARSTACK HIGH SPEED LENGTH (MM)
2084261502	150
2084261503	200
2084261504	300
2084261505	400
2084261506	450
2084261507	500

1X2 BELLY TO BELLY  
BOTTOM OF BOARD

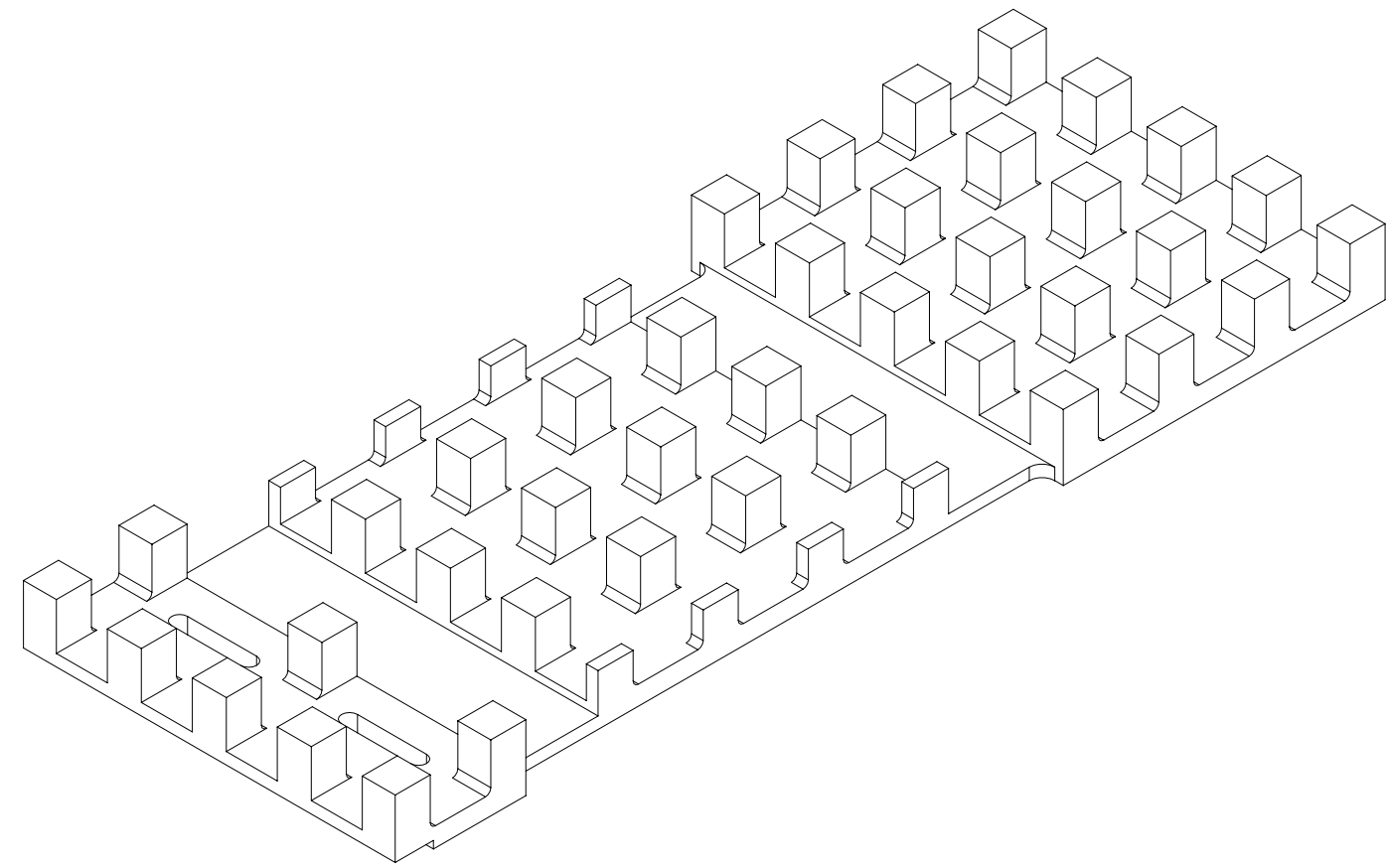
PART NUMBER	NEARSTACK HIGH SPEED LENGTH (MM)
2084262502	150
2084262503	200
2084262504	300
2084262505	400
2084262506	450
2084262507	500

NOTES:

1. ALL CABLE PART NUMBERS LISTED ARE OF THE ZQ GEN 2.0 AND NEARSTACK GEN 2.0 DESIGN .
2. CONTACT MOLEX FOR BIPASS ASSEMBLY PART NUMBERS AND AVAILABILITY FOR 1X3 THROUGH 1X6 CONFIGURATIONS

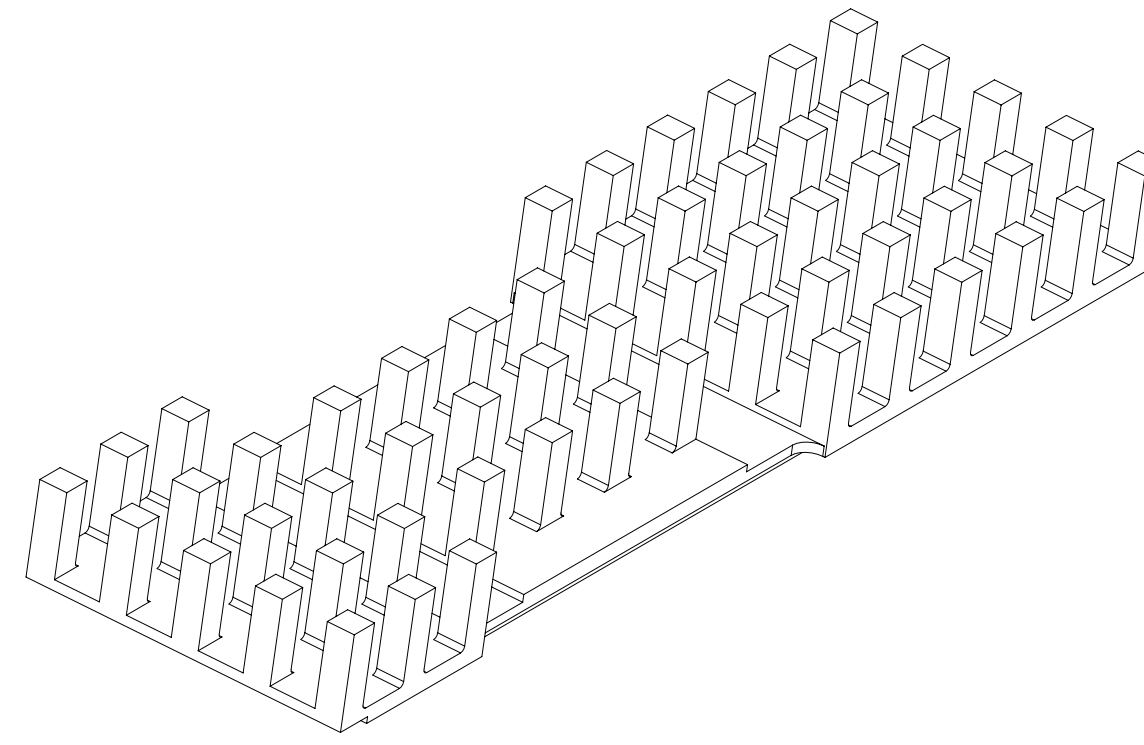
<b>SYMBOLS</b> = 0 = 0 = 0 = 0 = 0 = 0 = 0 = 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: UPDATE NOTES 5 FOR CLARIFICATION SHALL MATE GEN 2.0 BIPASS WITH GEN 2.0 PLUG		  <b>ZQSFP BIPASS P2B 1XN POWER TO BOARD</b>  PRODUCT CUSTOMER DRAWING	
	DIMENSION UNITS: <b>mm</b> SCALE: <b>2:1</b>	GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 701299 DRWN: LLI05 2022/03/02 CHK'D: BCHEN06 2022/04/08 APPR: BCHEN06 2022/04/08		
	ANGULAR TOL: ± °	4 PLACES ± 3 PLACES ± 2 PLACES ± 0.13 1 PLACE ± 0.25 0 PLACES ±		INITIAL REVISION: DRWN: SVANG01 2018/06/12 APPR: ADTUCKER 2018/11/09		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING: <b>D-SIZE</b>	SERIES: <b>208426</b>		MATERIAL NUMBER: <b>2084261000</b> CUSTOMER: <b>GENERAL MARKET</b>
DOCUMENT STATUS: P1 RELEASE DATE: 2022/04/08 04:59:14		DOCUMENT NUMBER: <b>2084261000</b> DOC TYPE: PSD DOC PART: 000 REVISION: G		SHEET NUMBER: <b>2 OF 9</b>		

STANDARD HEAT SINK  
USED ON ASSEMBLIES SHOWN  
IN THIS DRAWING

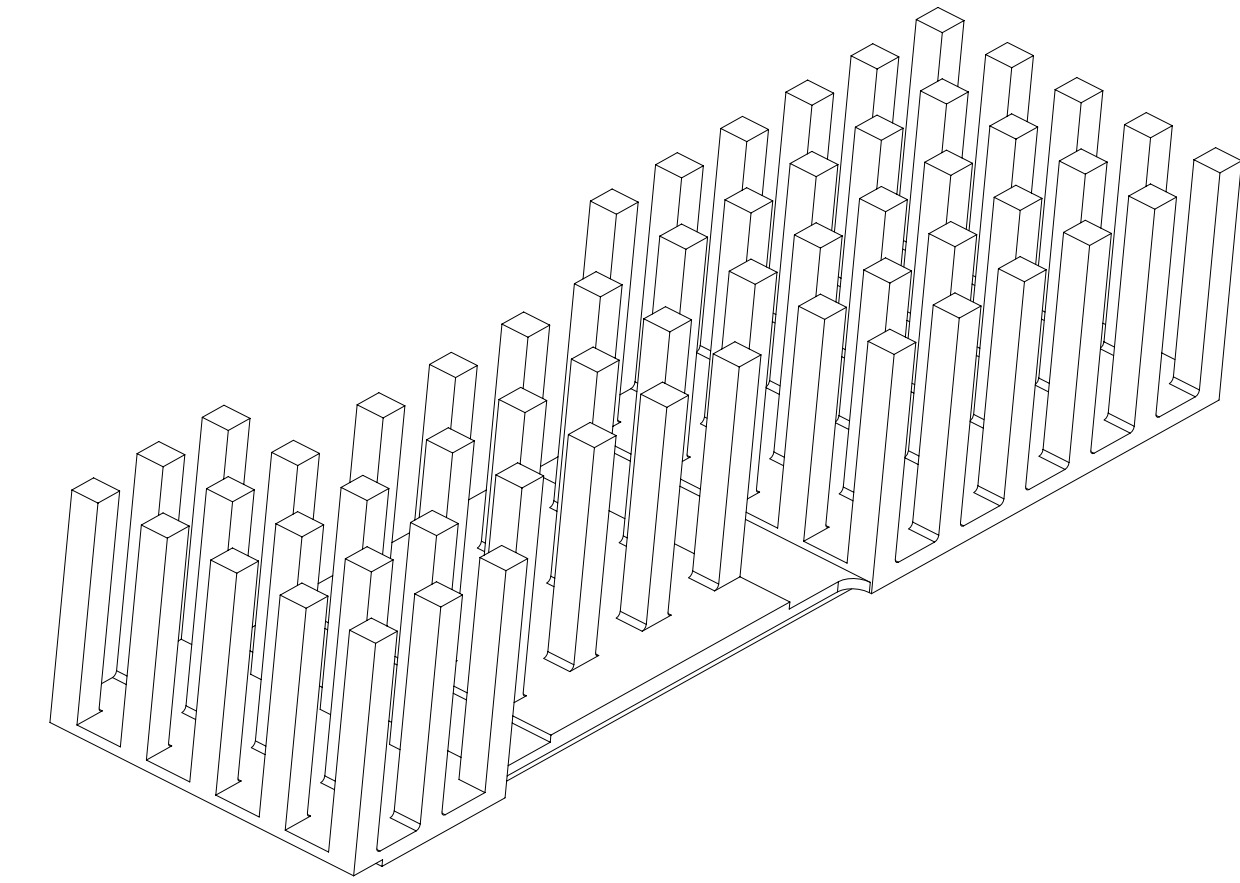


HEAT SINK PIN TYPE  
HEIGHT = 3.1MM

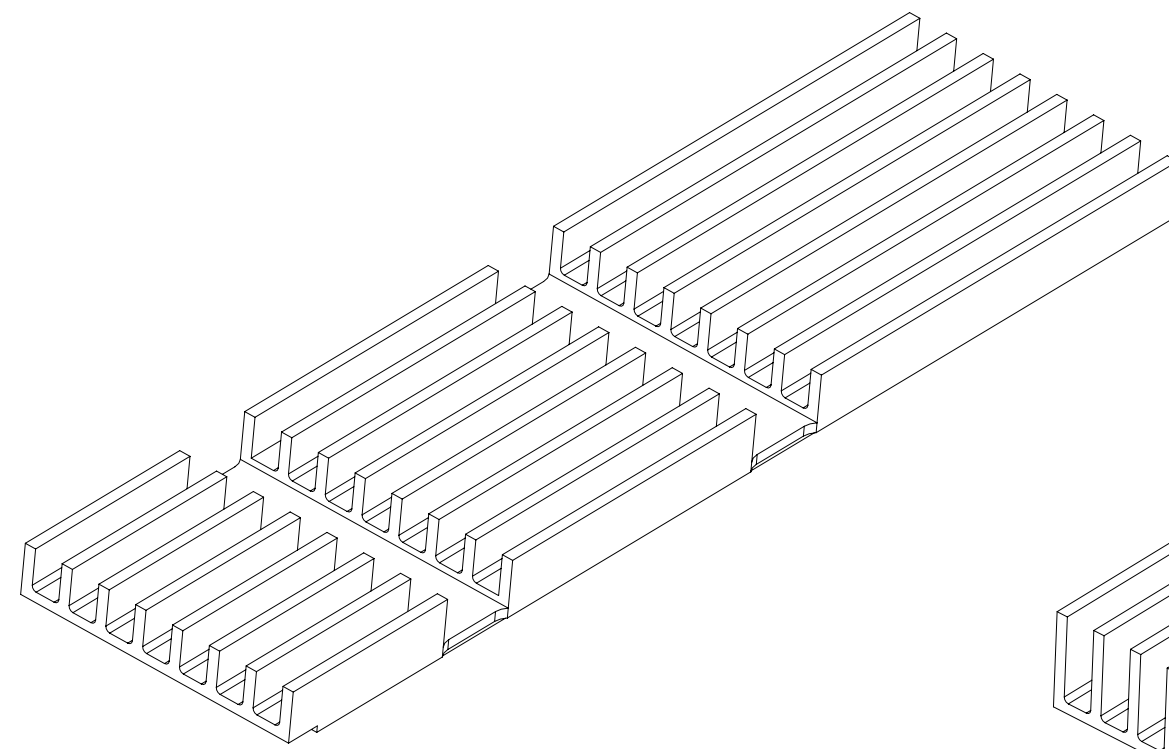
### HEAT SINK OPTIONS



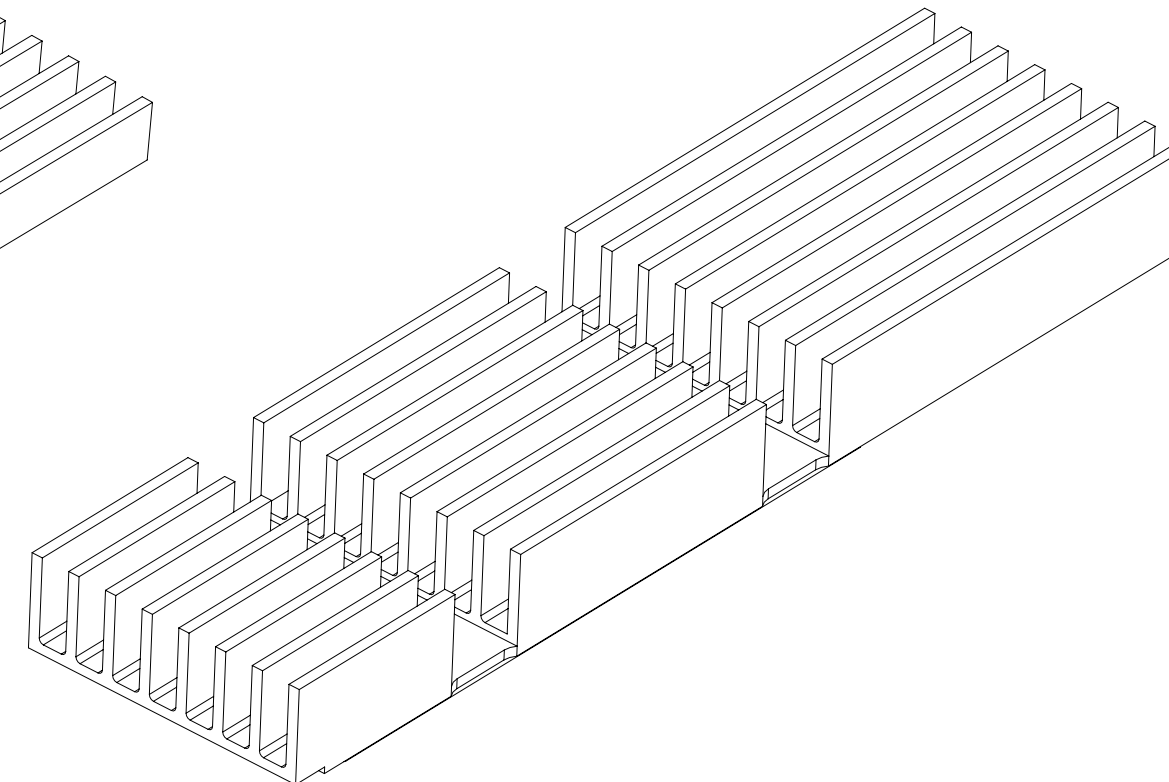
HEAT SINK PIN TYPE  
HEIGHT = 5.4MM



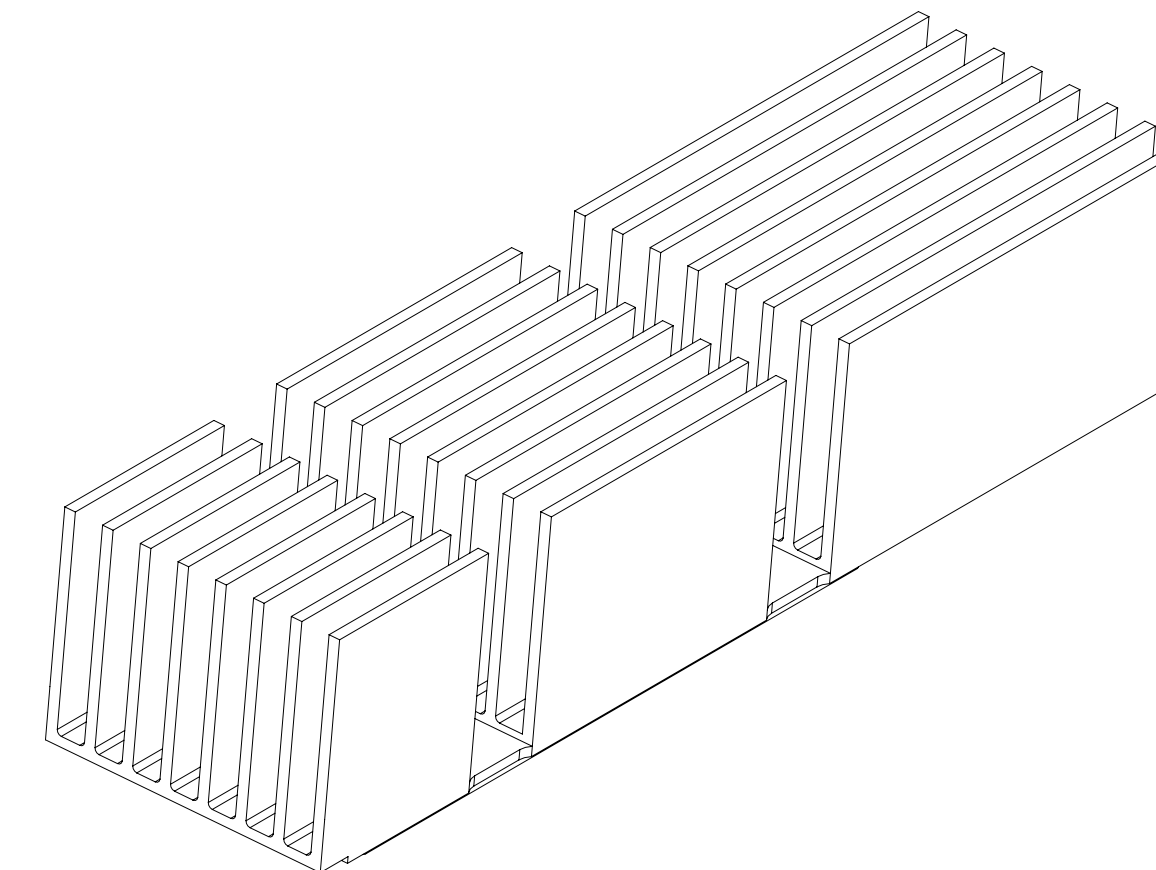
HEAT SINK PIN TYPE  
HEIGHT = 12.4MM



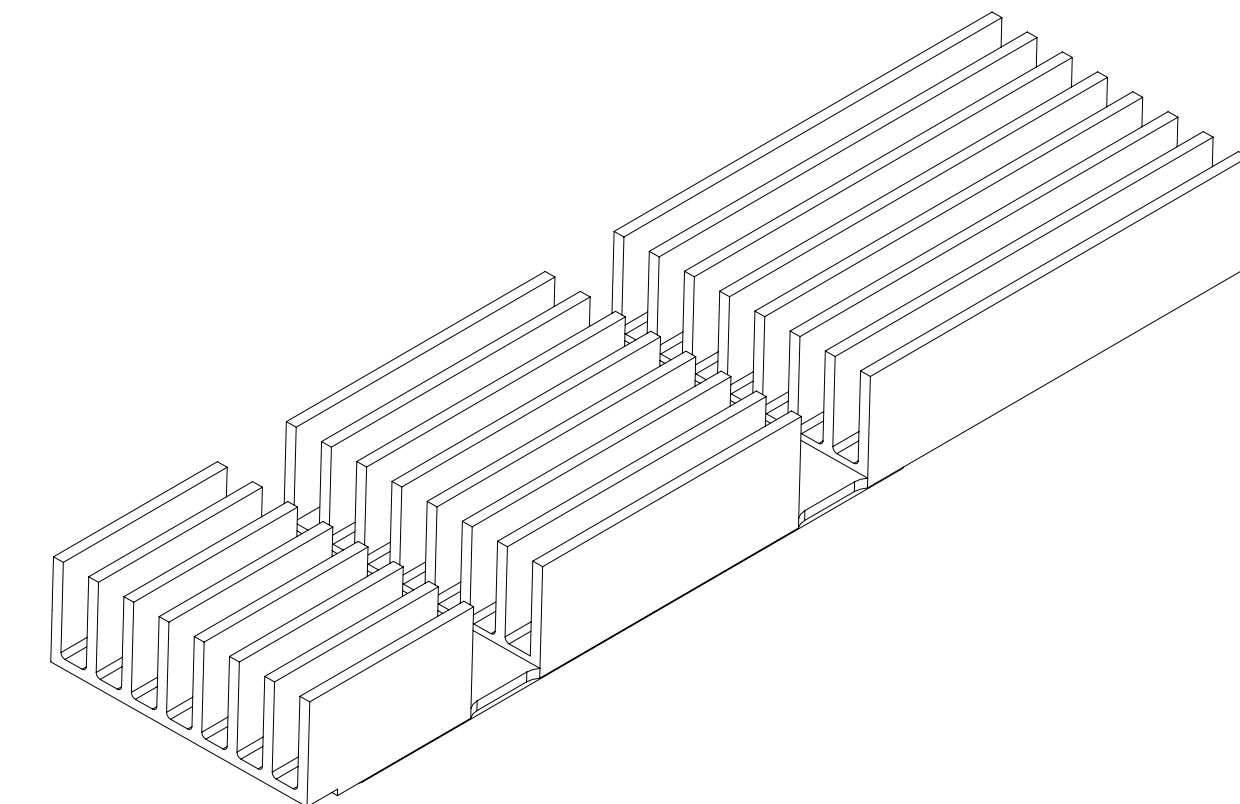
HEAT SINK FIN TYPE  
HEIGHT = 3.1MM



HEAT SINK FIN TYPE  
HEIGHT = 5.4MM



HEAT SINK FIN TYPE  
HEIGHT = 12.4MM



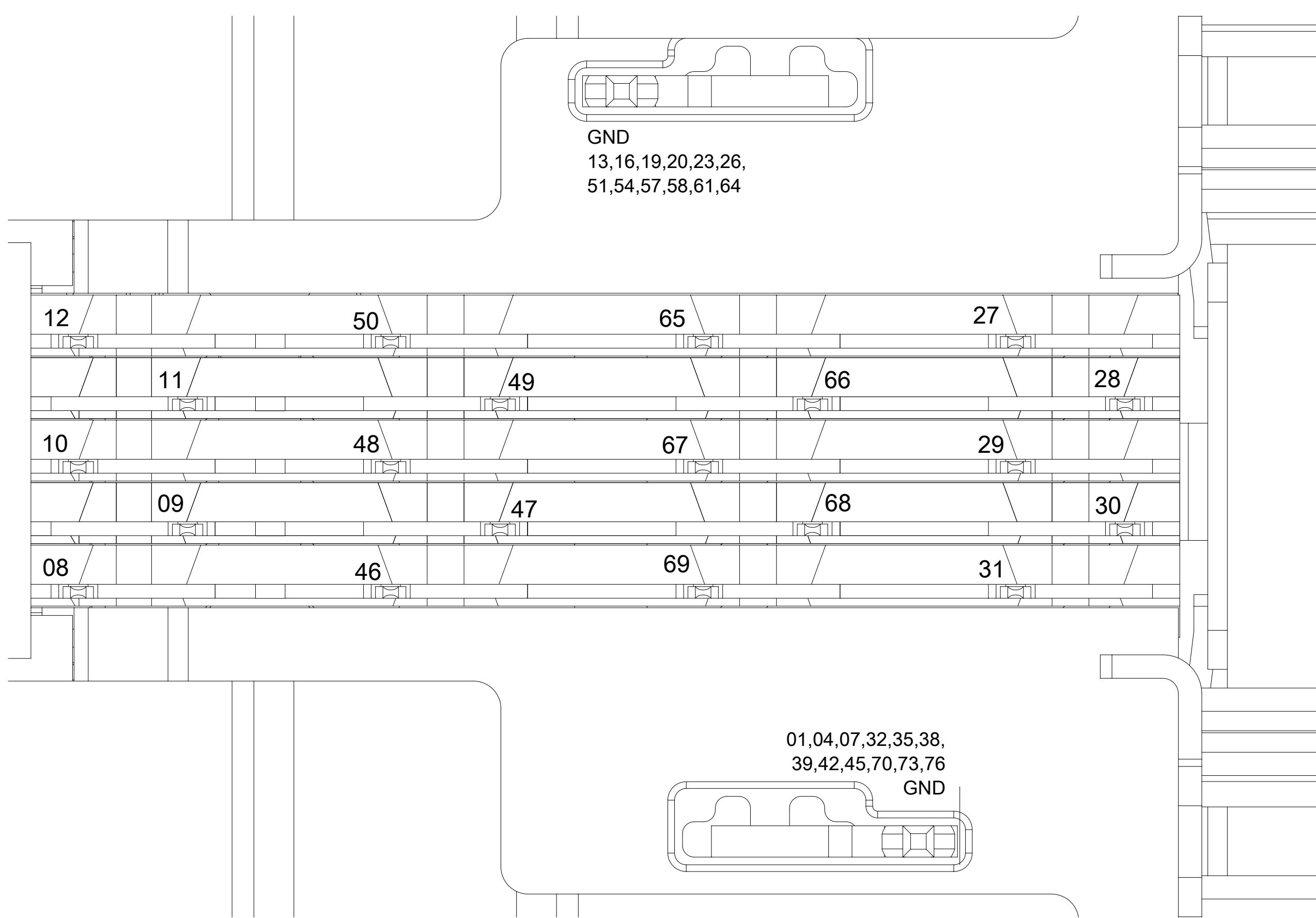
HEAT SINK FIN TYPE  
HEIGHT = 6.0MM

CONTACT MOLEX FOR BiPASS ASSEMBLY PART NUMBER AND AVAILABILITY

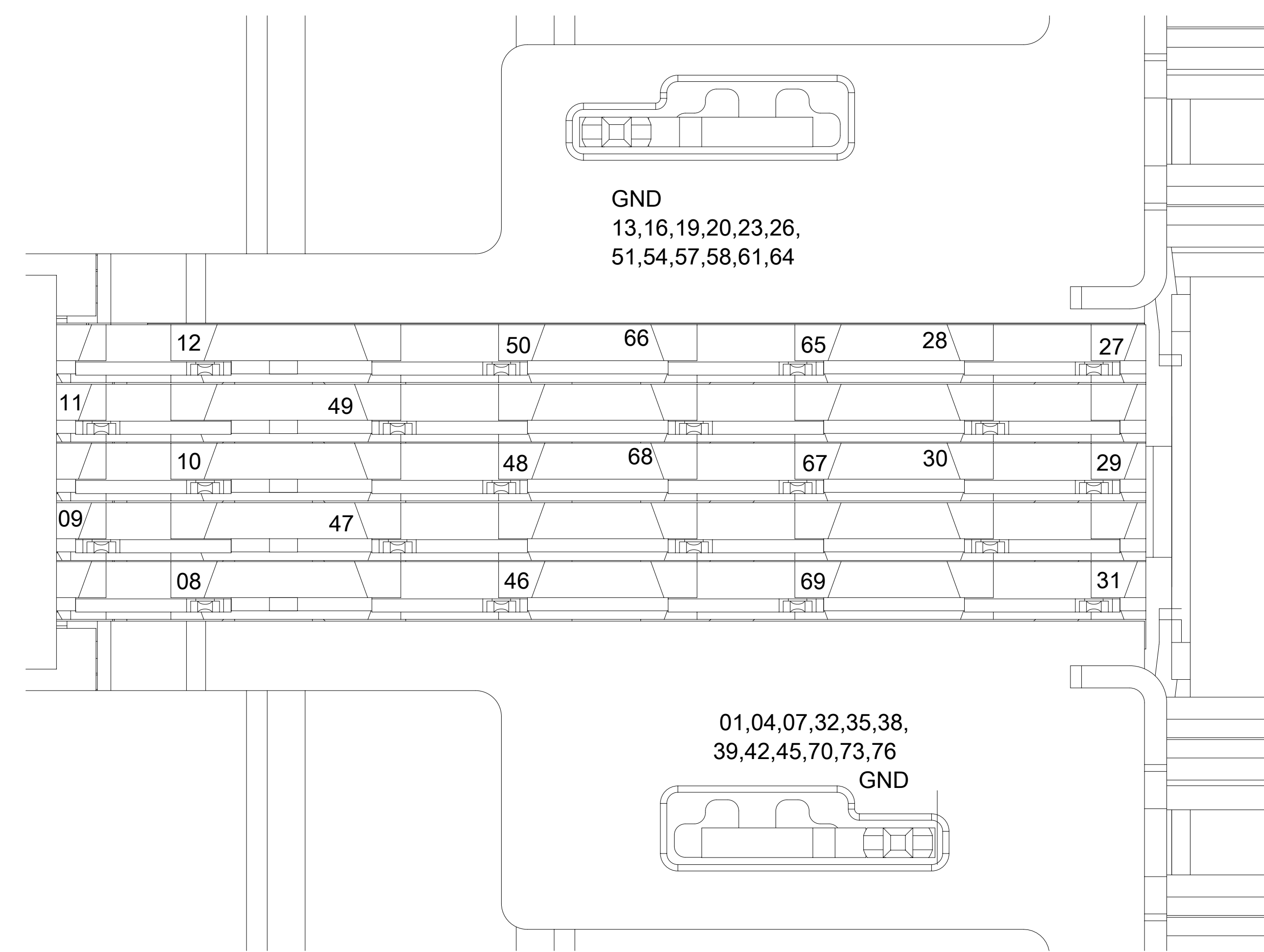
SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	DIMENSION UNITS	SCALE	CURRENT REV DESC: UPDATE NOTES 5 FOR CLARIFICATION SHALL MATE GEN 2.0 BIPASS WITH GEN 2.0 PLUG
▽ = 0	mm	1:1	EC NO: 701299 DRWN: LLI05 2022/03/02 CHK'D: BCHEN06 2022/04/08 APPR: BCHEN06 2022/04/08
▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		
▽ = 0	ANGULAR TOL	± °	INITIAL REVISION: DRWN: SVANG01 2018/06/12 APPR: ADTUCKER 2018/11/09
▽ = 0	4 PLACES	±	
▽ = 0	3 PLACES	±	DOCUMENT NUMBER <b>2084261000</b>
▽ = 0	2 PLACES	± 0.13	
▽ = 0	1 PLACE	± 0.25	DOC TYPE PSD
▽ = 0	0 PLACES	±	DOC PART 000
▽ = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	REVISION <b>G</b>
▽ = 0		DRAWING SERIES <b>D-SIZE 208426</b>	MATERIAL NUMBER SEE P/N TABLE
		CUSTOMER GENERAL MARKET	SHEET NUMBER 3 OF 9



P1 zQSFP STANDARD (TOP OF BOARD)  
 BOTTOM VIEW  
 POWER, LOW SPEED, GND



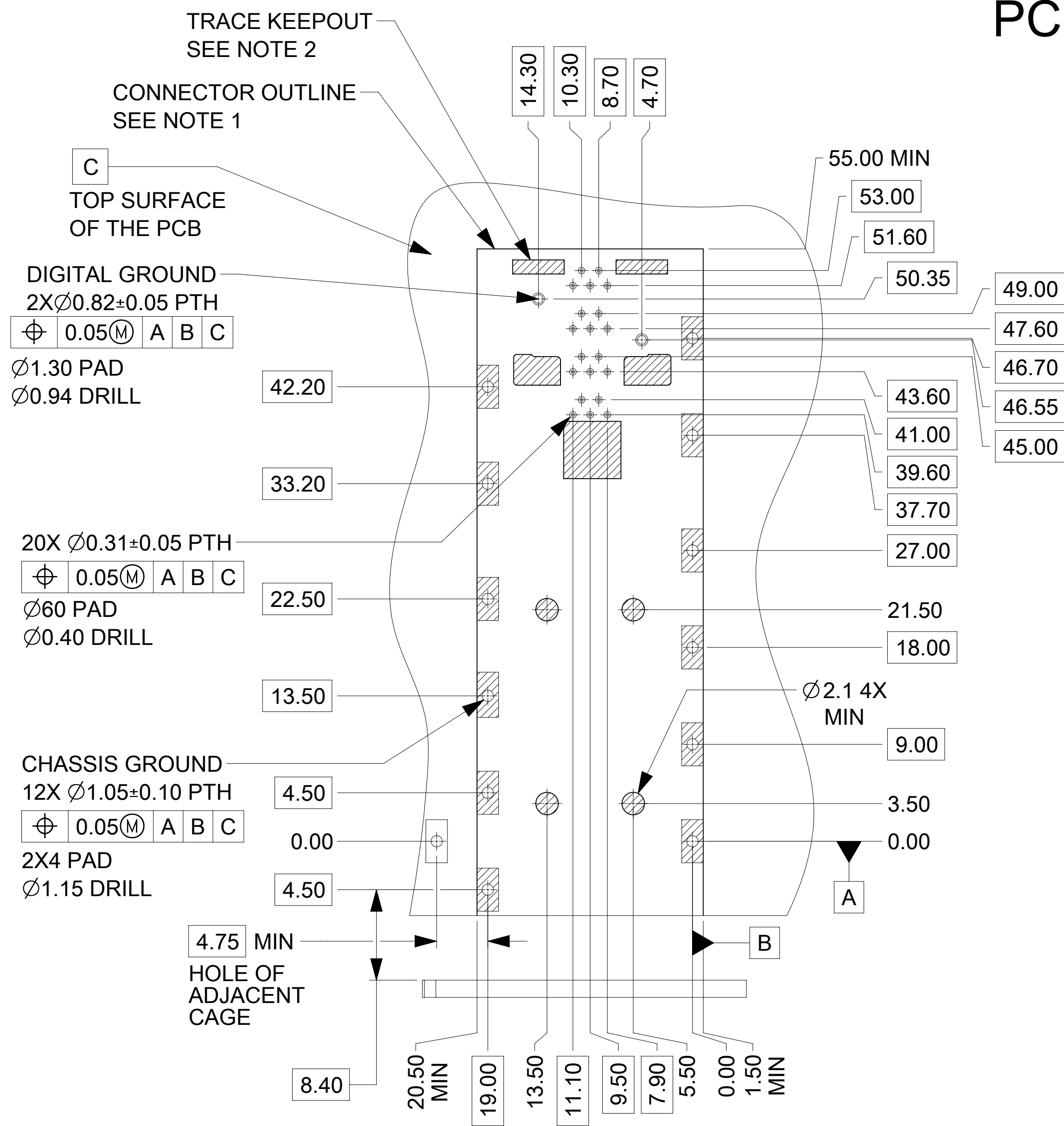
P1 zQSFP BELLY TO BELLY (BOTTOM OF BOARD)  
 BOTTOM VIEW  
 POWER, LOW SPEED, GND



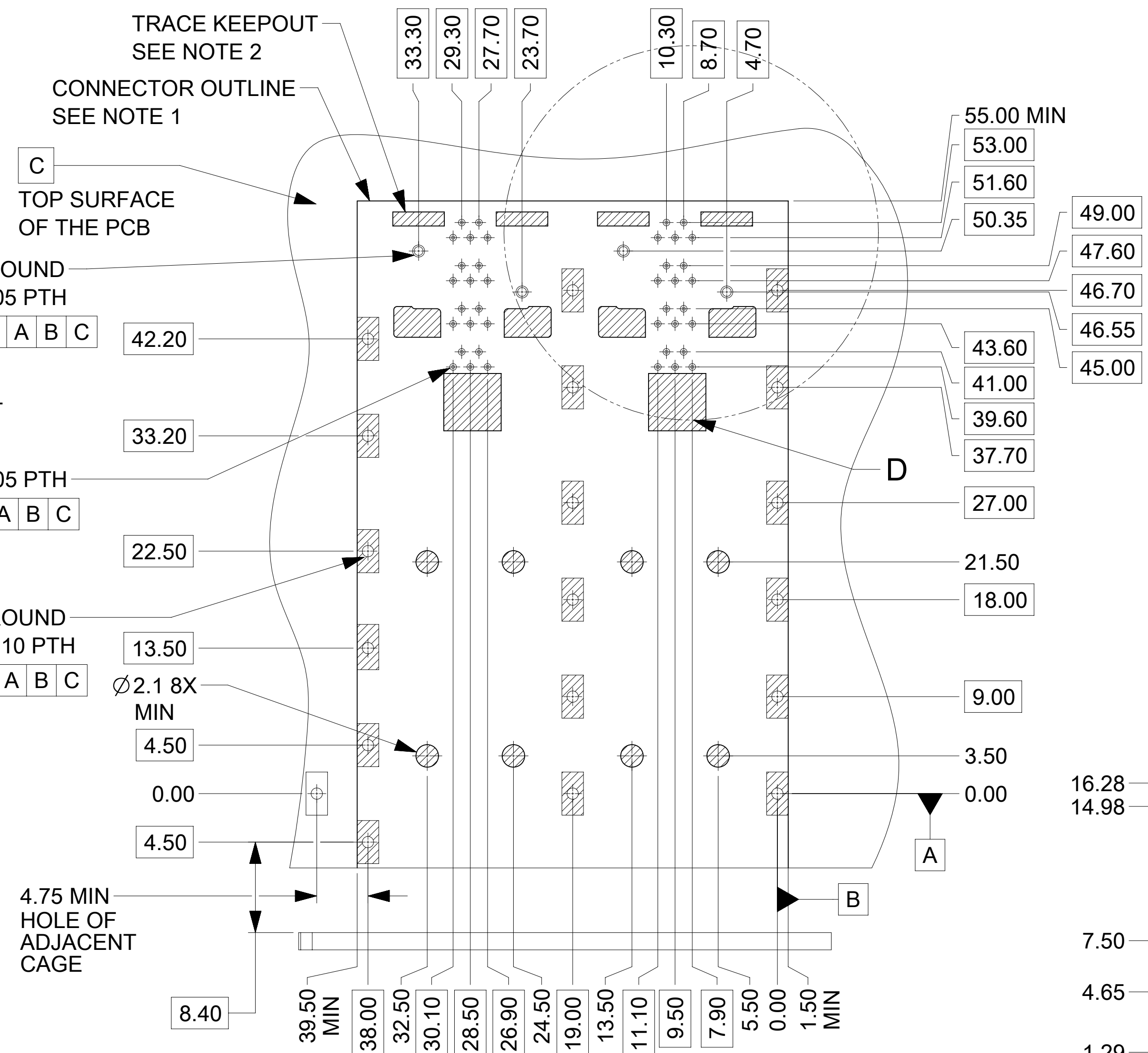
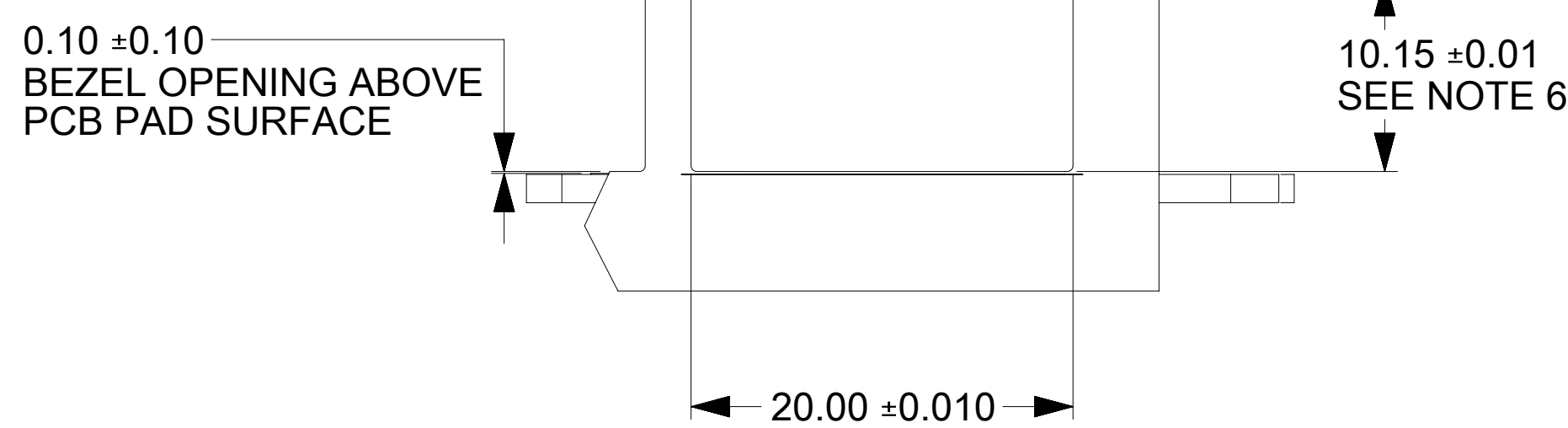
POWER & LOW SPEED SIGNALS	
P1 END	
PIN	SIGNAL
8	ModSelL
9	ResetL
10	VccRx
11	SCL
12	SDA
27	ModPrsL
28	IntL
29	VccTx
30	Vcc1
31	InitMode
46	NC
47	NC
48	NC
49	NC
50	NC
65	NC
66	NC
67	NC
68	NC
69	NC

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	GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 701299 DRWN: LLI05 2022/03/02 CHK'D: BCHEN06 2022/04/08 APPR: BCHEN06 2022/04/08		PRODUCT CUSTOMER DRAWING							
	ANGULAR TOL ± °		INITIAL REVISION:		DOCUMENT NUMBER: <b>2084261000</b>		DOC TYPE: PSD		DOC PART: 000		REVISION: G	
	4 PLACES ±		DRWN: SVANG01 2018/06/12 APPR: ADTUCKER 2018/11/09		MATERIAL NUMBER: <b>208426</b>		CUSTOMER: GENERAL MARKET		SHEET NUMBER: 5 OF 9			
	3 PLACES ±		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING: D-SIZE		SERIES: 208426			

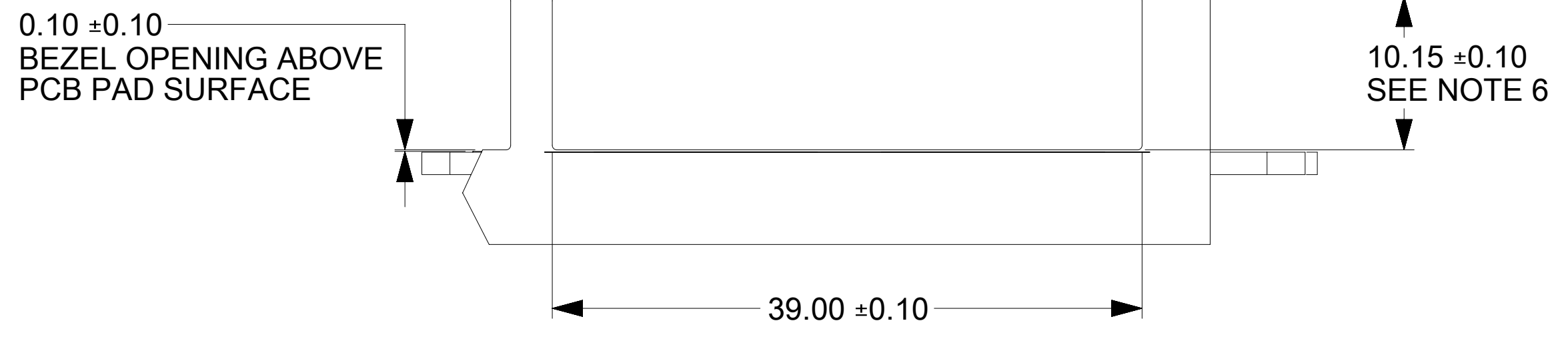
# PCB FOOTPRINT TOP OF BOARD



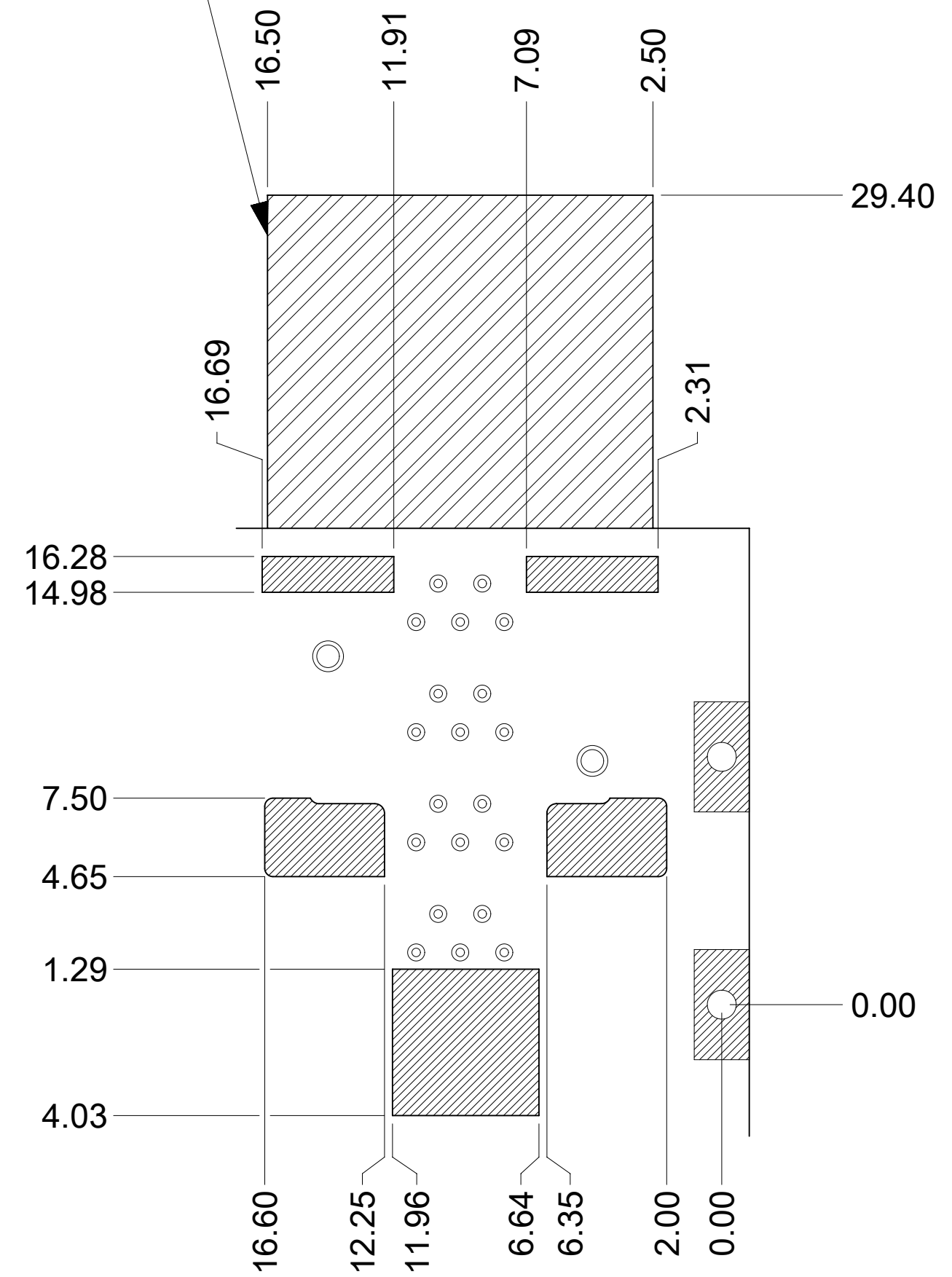
1X1 PCB LAYOUT



1X2 PCB LAYOUT



CABLE BUNDLE AREA, COMPONENTS MUST BE UNDER 1.06MM HT (TWINX MIN BEND RADIUS 5.6MM)

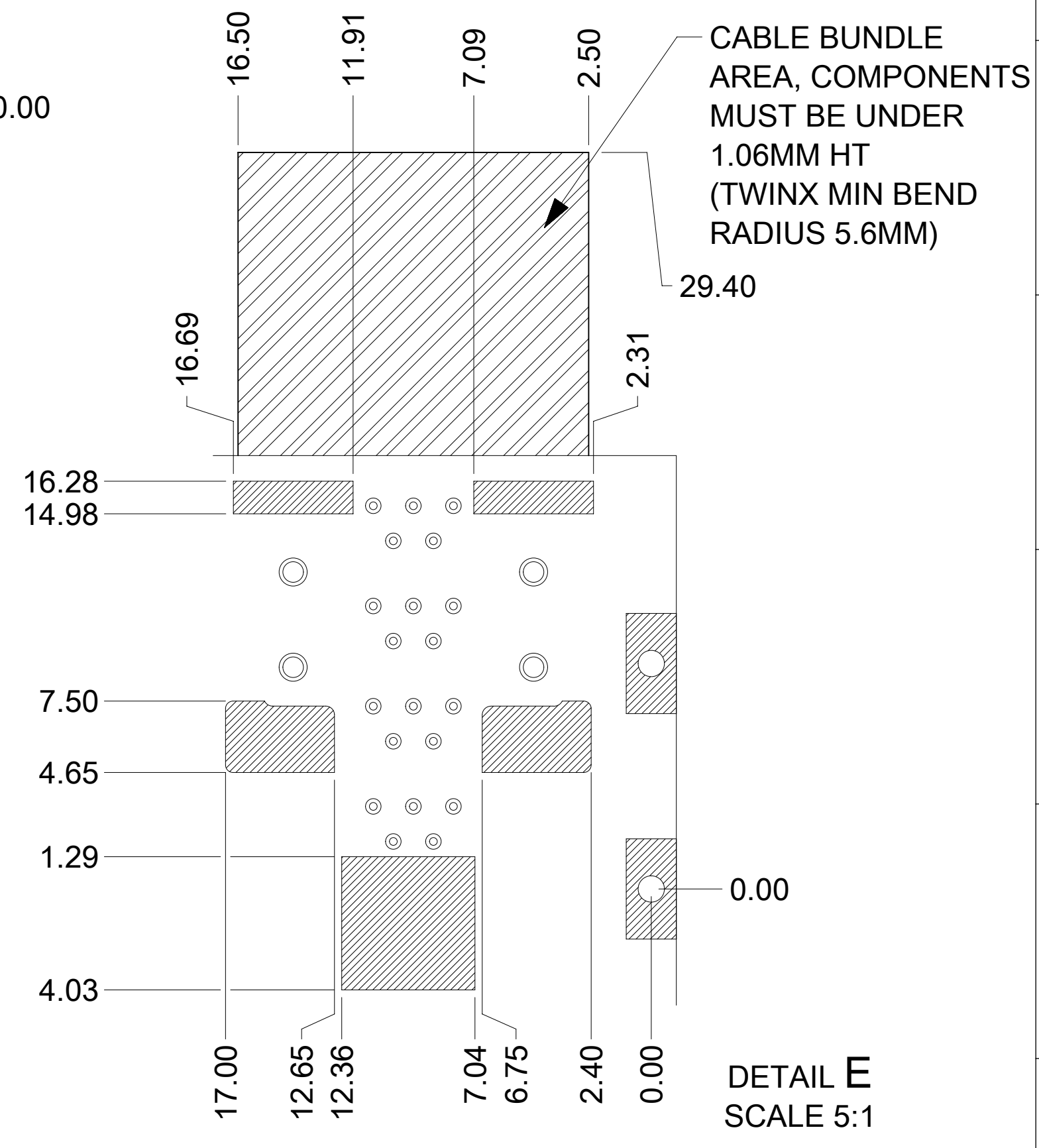
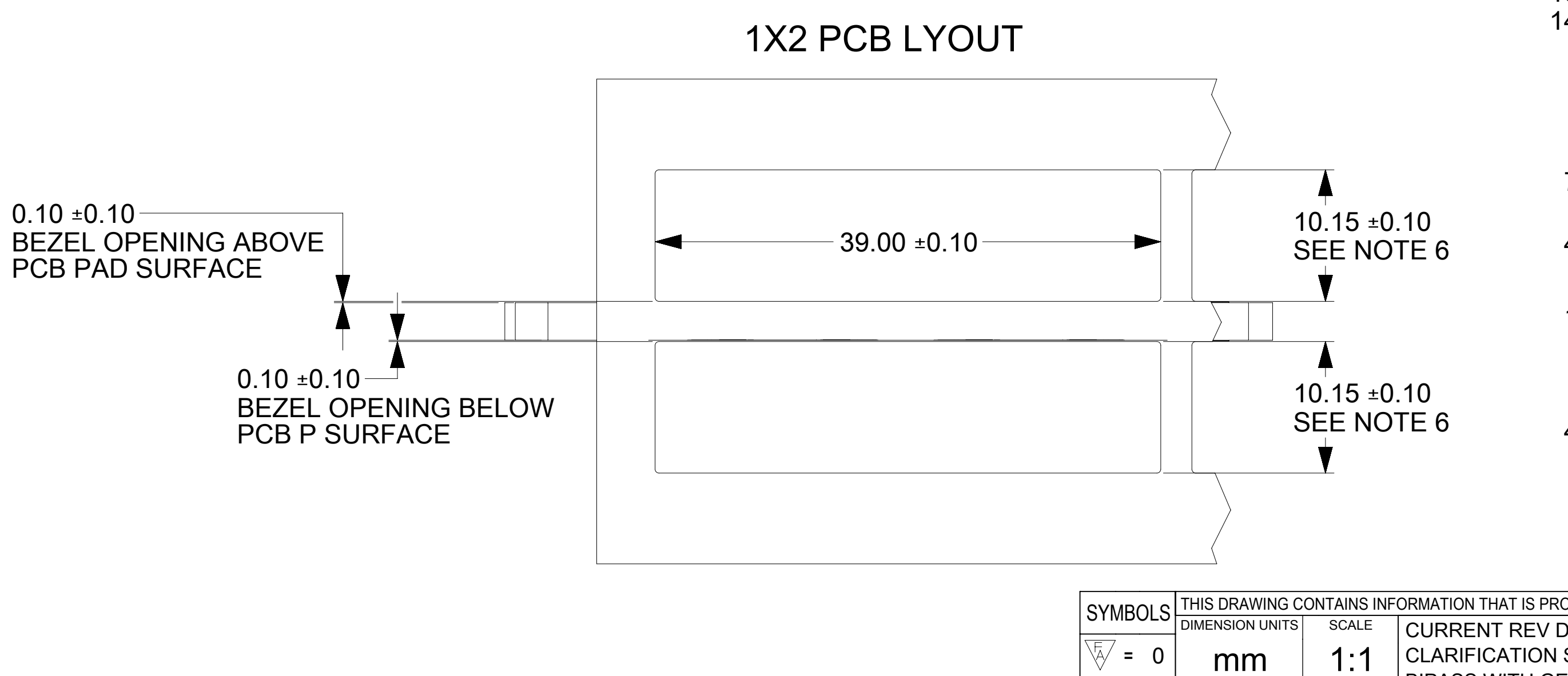
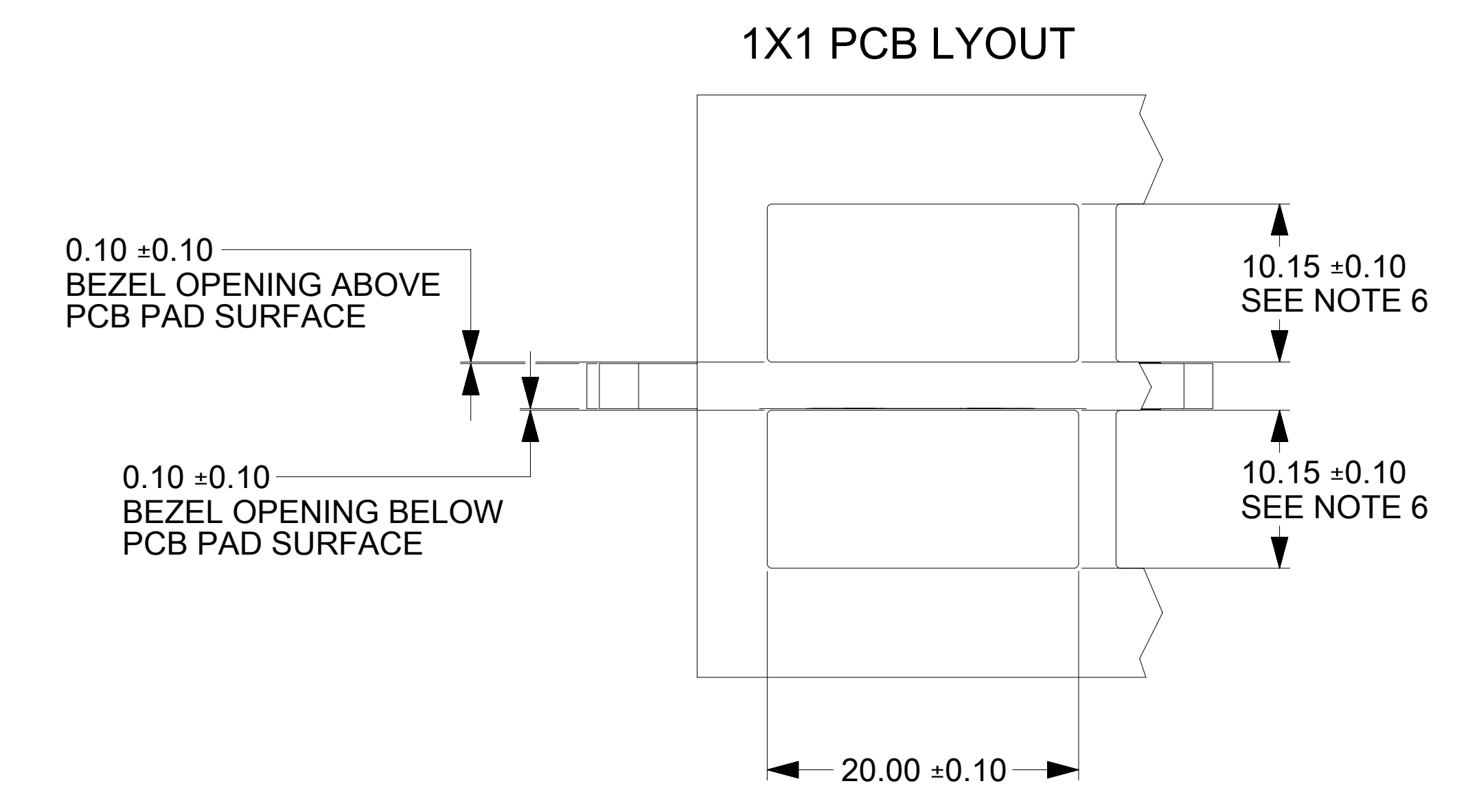
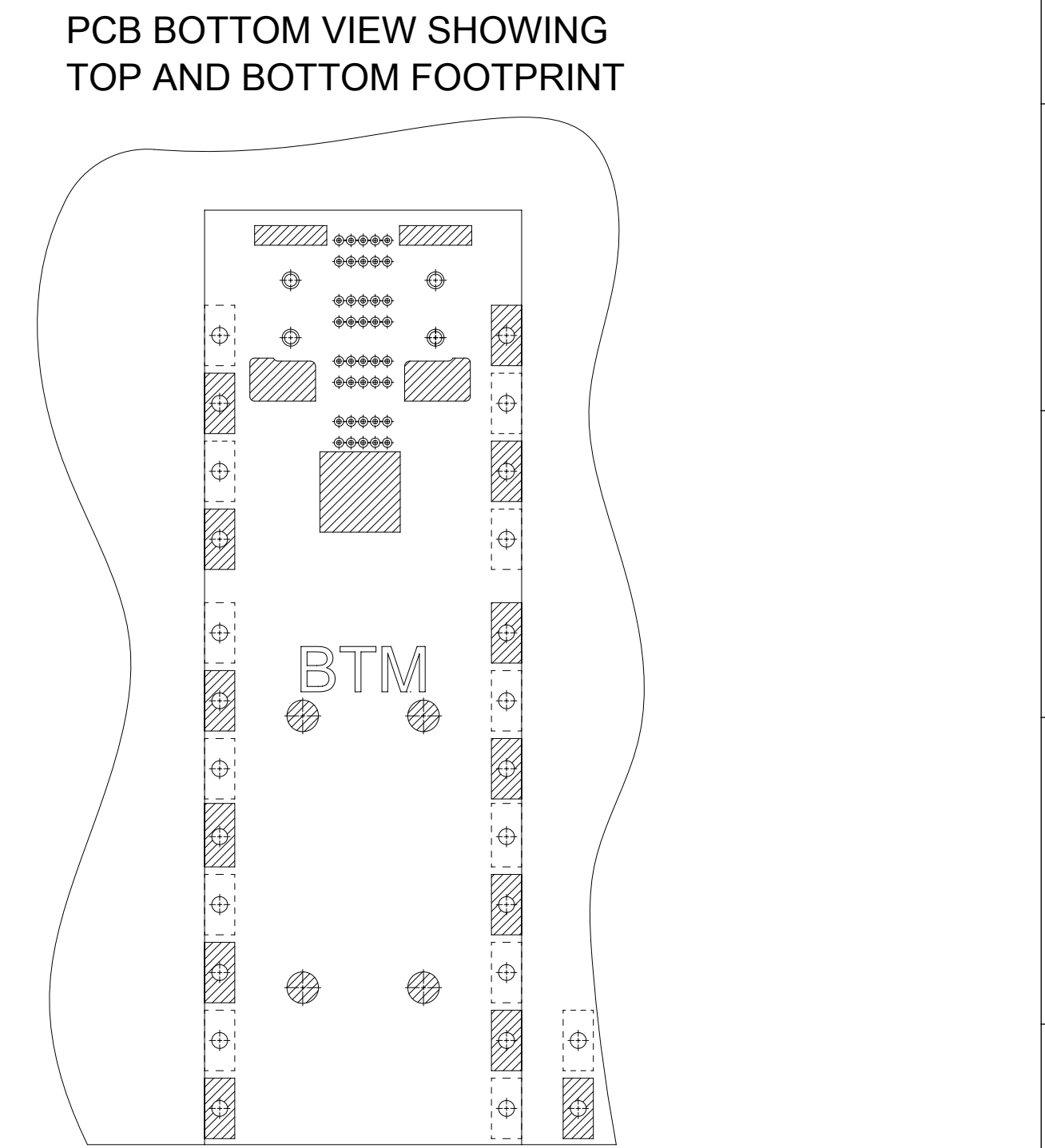
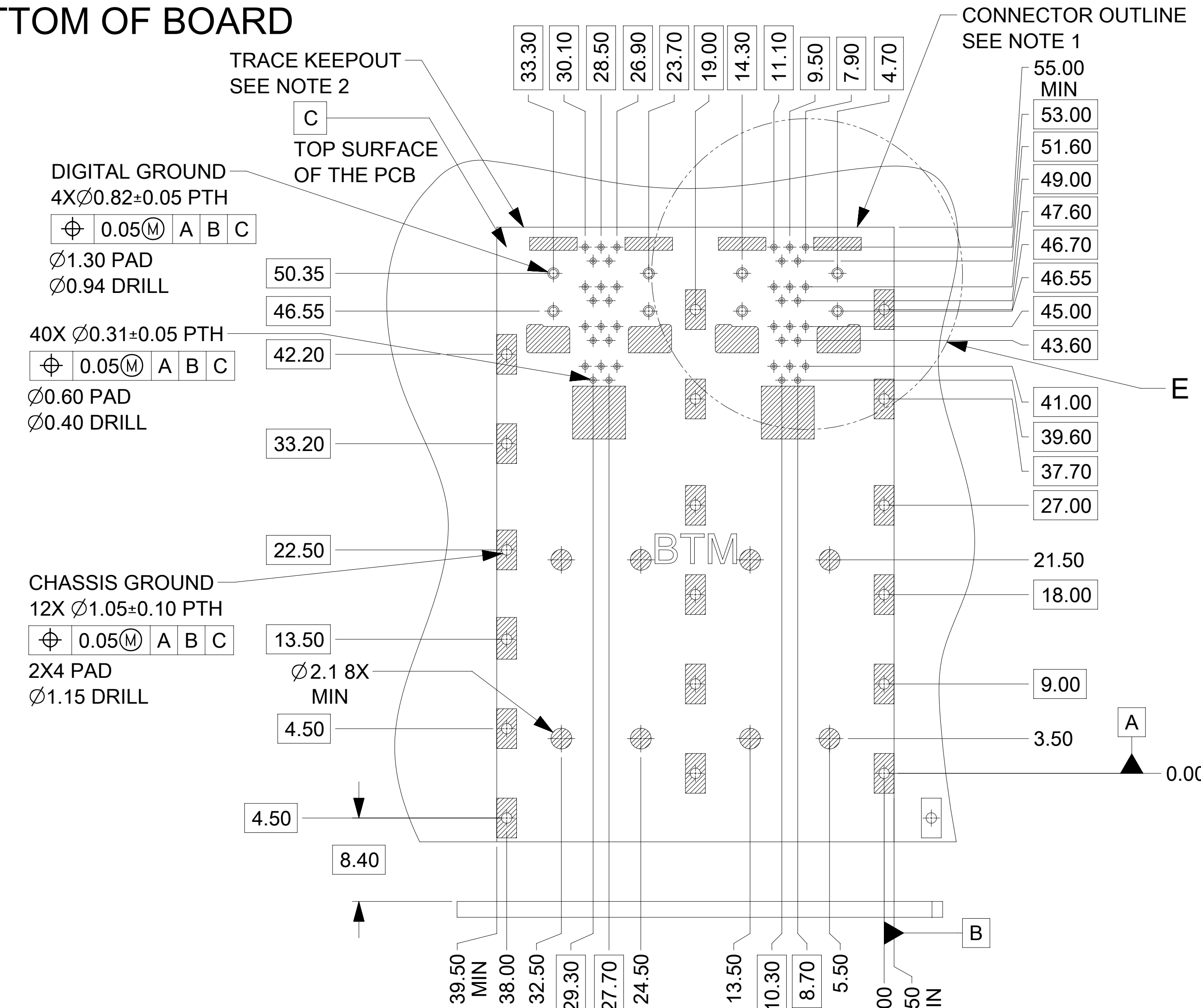
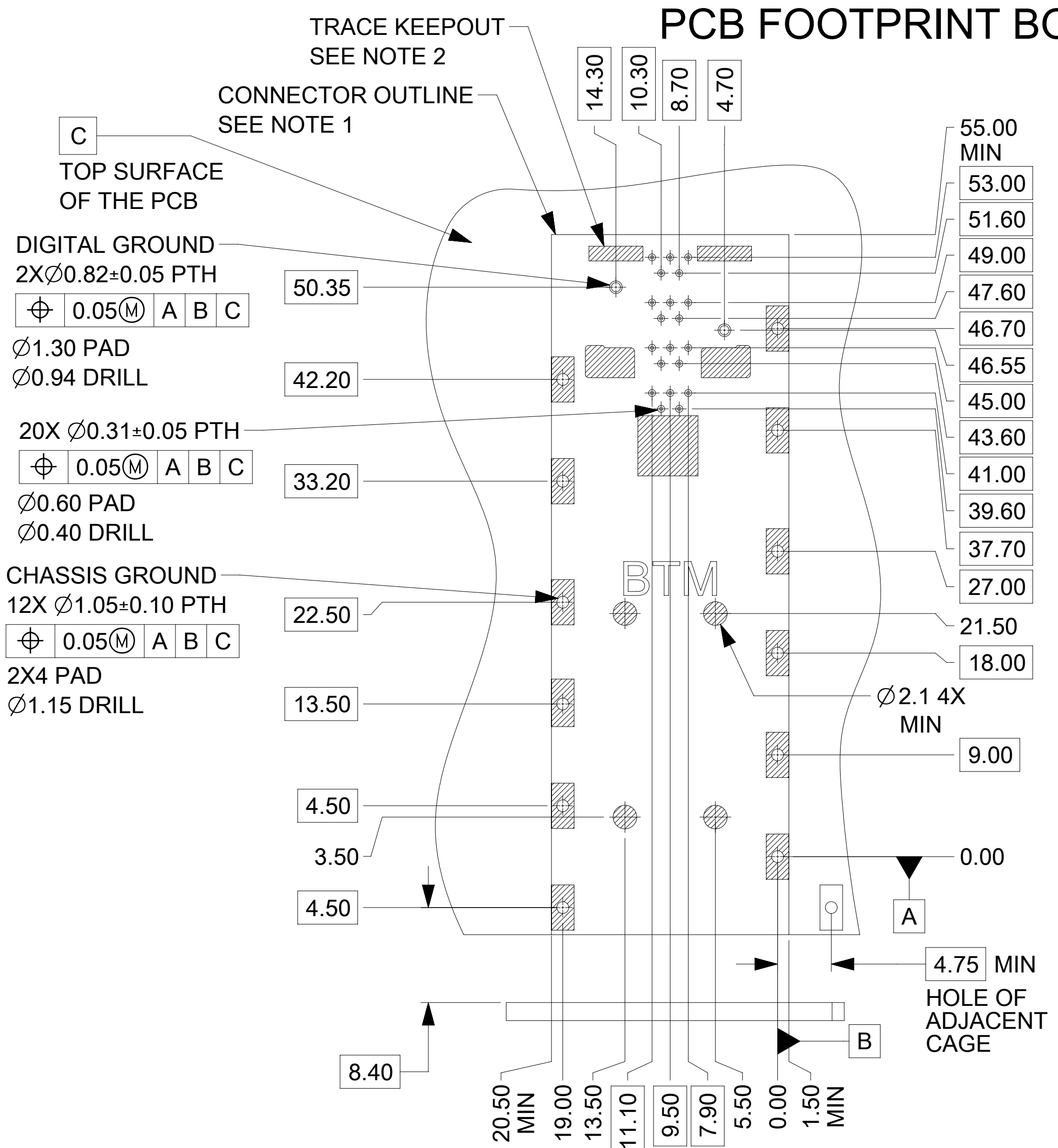


DETAIL D SCALE 5:1

- NOTES:
- DASHED LINES INDICATE THE CONNECTOR OUTLINE, THIS AREA IS A COMPONENT KEEP-OUT ZONE.
  - CROSS HATCHED AREAS DENOTE WHERE CAGE OR CONNECTOR HOUSINGS CAN CONTACT THE BOARD. THESE ARE TRACE KEEP-OUT ZONES.
  - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
  - 1.57 [0.062] MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.
  - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.

SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	DIMENSION UNITS	SCALE
$\nabla = 0$	mm	1:1
$\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)	
$\nabla = 0$	ANGULAR TOL	$\pm$ °
$\nabla = 0$	4 PLACES	$\pm$
$\nabla = 0$	3 PLACES	$\pm$
$\nabla = 0$	2 PLACES	$\pm 0.13$
$\nabla = 0$	1 PLACE	$\pm 0.25$
$\nabla = 0$	0 PLACES	$\pm$
$\square = 0$	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
$\nabla = 0$	THIRD ANGLE PROJECTION	DRAWING SERIES
		D-SIZE 208426
	CURRENT REV DESC: UPDATE NOTES 5 FOR CLARIFICATION SHALL MATE GEN 2.0 BIPASS WITH GEN 2.0 PLUG	EC NO: 701299
		DRWN: LLI05 2022/03/02
		CHK'D: BCHEN06 2022/04/08
		APPR: BCHEN06 2022/04/08
	INITIAL REVISION:	
	DRWN: SVANG01 2018/06/12	
	APPR: ADTUCKER 2018/11/09	
	DOCUMENT NUMBER	
	2084261000	
	DOC TYPE	DOC PART
	PSD	000
	REVISION	G
	PRODUCT CUSTOMER DRAWING	
	MATERIAL NUMBER	CUSTOMER
	SEE P/N TABLE	GENERAL MARKET
	SHEET NUMBER	
	6 OF 9	

# PCB FOOTPRINT BOTTOM OF BOARD



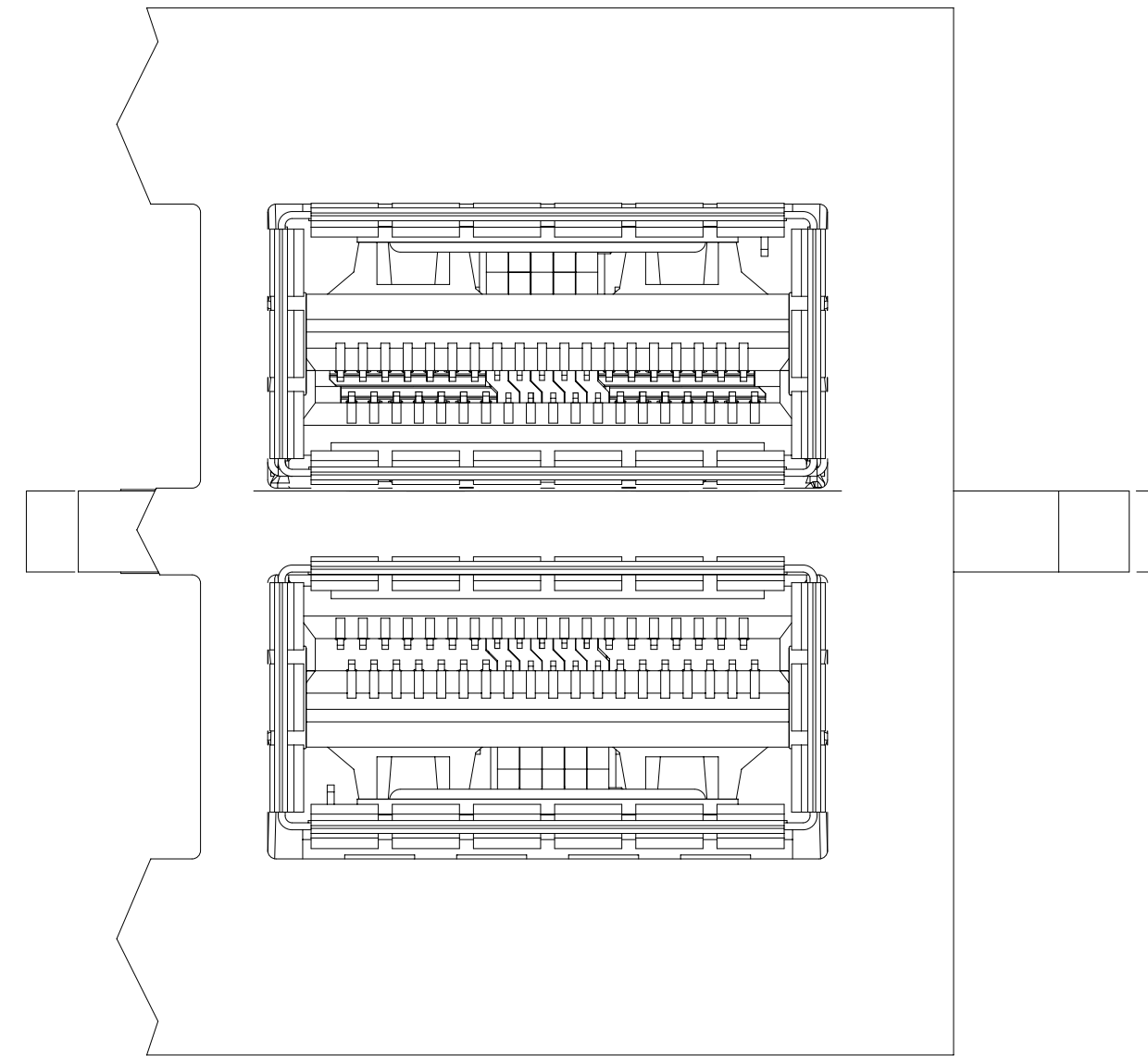
- NOTES:**
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  - CROSS HATCHED AREAS DENOTE WHERE CAGE OR CONNECTOR HOUSINGS CAN CONTACT THE BOARD. THESE AREAS ARE TRACE KEEP-OUT ZONES.
  - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
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$\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRWN: LLI05 2022/03/02
$\nabla = 0$	ANGULAR TOL	$\pm$	CHK'D: BCHEN06 2022/04/08
$\nabla = 0$	4 PLACES	$\pm$	APPR: BCHEN06 2022/04/08
$\nabla = 0$	3 PLACES	$\pm$	INITIAL REVISION:
$\nabla = 0$	2 PLACES	$\pm 0.13$	DRWN: SVANG01 2018/06/12
$\nabla = 0$	1 PLACE	$\pm 0.25$	APPR: ADTUCKER 2018/11/09
$\nabla = 0$	0 PLACES	$\pm$	
$\square = 0$	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	SERIES
$\nabla = 0$			D-DRAWING
			D-SIZE 208426
DOCUMENT STATUS		P1	RELEASE DATE
P1		2022/04/08	04:59:14
molex		ZQSFP BIPASS P2B 1XN POWER TO BOARD	
PRODUCT CUSTOMER DRAWING		DOCUMENT NUMBER	
2084261000		DOC TYPE	DOC PART
PSD		000	G
GENERAL MARKET		SHEET NUMBER	
7 OF 9			

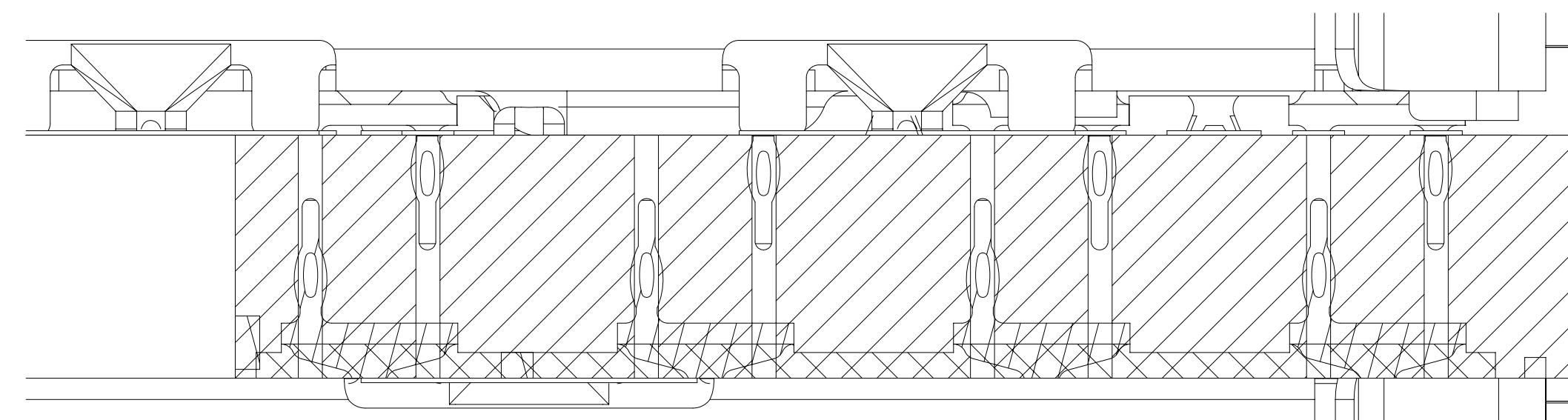
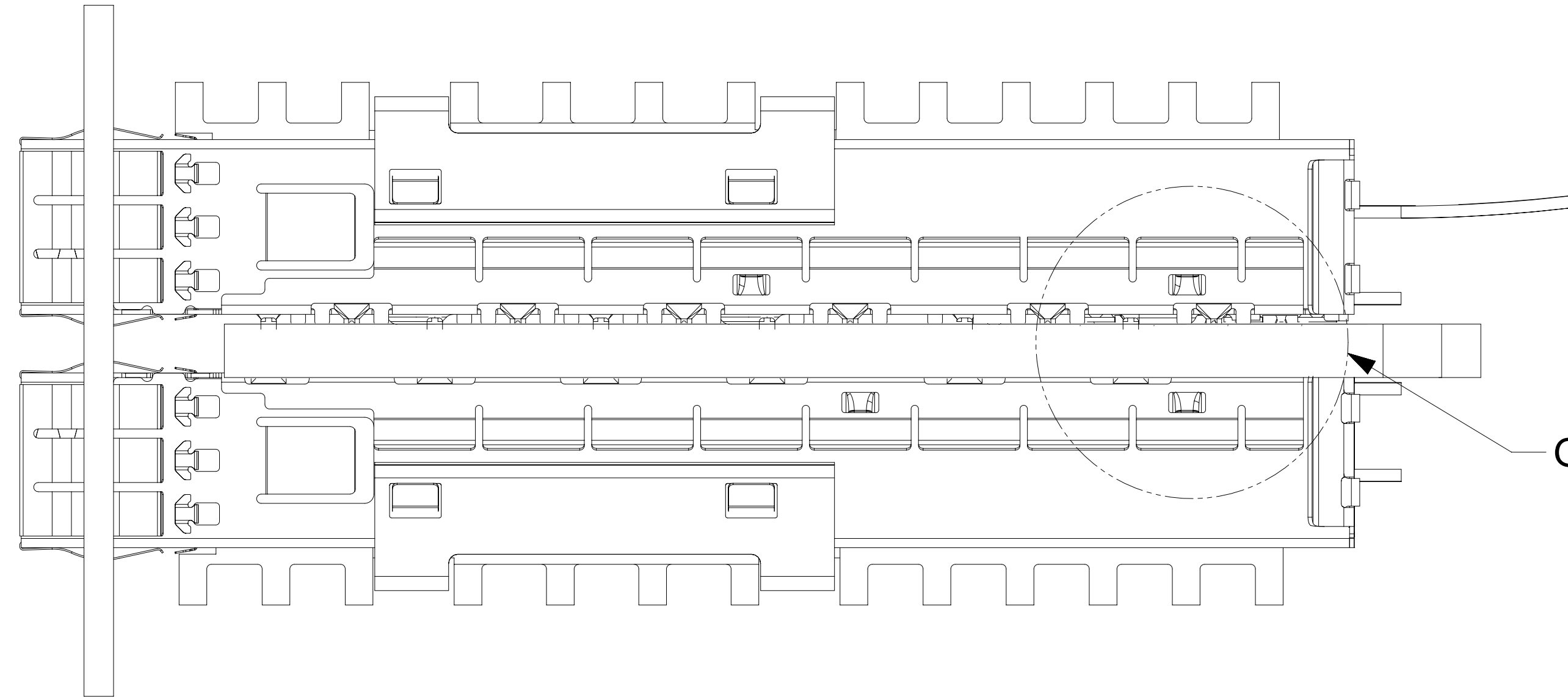




TOP OF BOARD  
PN# 20842610\*\*



BOTTOM POSITION  
PN# 20842615\*\*



DETAIL G  
CUTAWAY DOWN TO SIGNAL PINS  
SCALE 15:1

SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	DIMENSION UNITS	SCALE	CURRENT REV DESC: UPDATE NOTES 5 FOR CLARIFICATION SHALL MATE GEN 2.0 BIPASS WITH GEN 2.0 PLUG
= 0	mm	5:1	EC NO: 701299 DRWN: LLI05 2022/03/02 CHK'D: BCHEN06 2022/04/08 APPR: BCHEN06 2022/04/08
= 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		
= 0	ANGULAR TOL	± °	INITIAL REVISION: DRWN: SVANG01 2018/06/12 APPR: ADTUCKER 2018/11/09
= 0	4 PLACES	±	
= 0	3 PLACES	±	DOCUMENT NUMBER: 2084261000 DOC TYPE: PSD DOC PART: 000 REVISION: G
= 0	2 PLACES	± 0.13	
= 0	1 PLACE	± 0.25	MATERIAL NUMBER: 208426 CUSTOMER: GENERAL MARKET SHEET NUMBER: 9 OF 9
= 0	0 PLACES	±	
= 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING: D-SIZE SERIES: 208426
= 0			

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ZQSFP BIPASS P2B 1XN POWER TO BOARD

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: 2084261000  
DOC TYPE: PSD  
DOC PART: 000  
REVISION: G

MATERIAL NUMBER: 208426  
CUSTOMER: GENERAL MARKET  
SHEET NUMBER: 9 OF 9